

SOT1314-1

plastic very thin small outline package; no leads; 4 terminals
8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	VSON4
Package type industry code	VSON4
Package style descriptive code	BCC (bottom chip carrier)
Package style suffix code	U (UTLP based)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	4-11-2011

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		4.9	-	5	5.1	mm
E	package width		3.1	-	3.2	3.3	mm
A	seated height		0.8	-	1	0.85	mm
e	nominal pitch		-	-	2.54	-	mm
n ₂	actual quantity of termination		-	-	4	-	

2. Package outline

Fig. 1. Package outline VSON4 (SOT1314-1)



3. Legal information

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